

AMENDMENTS TO THE CLAIMS

Claims 1-15 (cancelled)

16. (previously presented) A method of making an IC chip package having a first IC chip with an active surface, the active surface having extending therefrom an electrical connector in electrical communication with the first IC chip, the first IC chip being mounted upon a first side of a board-on-chip (BOC) substrate having said first side that is opposite a second side thereof, the method comprising:

providing a second IC chip having an active surface and being disposed over the first side of the BOC substrate;

providing a container disposed upon the BOC substrate, the container in contact with the active surface of the first IC chip; and

injecting a grease between the BOC substrate and the container;

wherein the grease:

is in contact with the electrical connector and with the active surfaces of each of the first and second IC chips; and

is enclosed within the container and the substrate.

17. (original) The method as defined in Claim 16, further comprising:

providing a third IC chip having an active surface and being disposed over the first side of the BOC substrate and over the second IC chip such that the grease is in contact with the active surface of the third IC chip.

18. (previously presented) The method as defined in Claim 17, further comprising:  
operating the first, second, and third IC chips to generate heat therefrom; and  
conducting the heat from the electrical connector and from the first, second, and  
third IC chips to the grease, to the container, and to the ambient.
19. (original) The method as defined in Claim 16, wherein the grease has:  
a thermal conductivity in a range from about 2 Watts/m·K to about 5 Watts/m·K;  
a dielectric constant in a range from less than about 6 to about 9; and  
a melting point in a range from about 190° C to about 220° C.
20. (original) The method as defined in claim 16, further comprising:  
generating heat from at least one of the IC chips by operating said at least one of  
the IC chips; and  
allowing the heat to propagate to the grease and to the container.
21. (previously presented) The method as defined in Claim 16, further comprising:  
securing the container to the substrate with a dam structure that contacts the  
grease.

22. (previously presented) The method as defined in Claim 16, further comprising:  
operating the first and second IC chips to generate heat therefrom; and  
conducting the heat from the IC chips and the electrical connector to the grease, to  
the container, and to the ambient.
23. (previously presented) The method as defined in Claim 16, wherein the grease  
has a thermal conductivity that is less than a thermal conductivity of the container.
24. (previously presented) The method as defined in Claim 16, wherein the IC chip  
package comprises IC chip elements, wherein the container disposed upon the substrate encloses  
a volume external to the IC chip elements, and wherein the injecting a grease comprises filling  
with the grease the volume enclosed by the container.
25. (previously presented) The method as defined in Claim 16, wherein the container  
comprises a metal that has a thermal conductivity greater than the thermal conductivity of the  
grease.

Claims 26-33 (cancelled)